



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Daniel Yap)	Group Art No.: 2827
Application No:	10/053,159)	Examiner: Thai, Luan C.
Filed:	01/15/2002)	Re: Rule 312 Amendment
For:	"Precision Electroplated Solder Bumps...")	Our Ref: B-3752DIV 619413-2
)	Date: March 4, 2004

Mail Stop Issue Fee
Commissioner for Patents
POB 1450
Alexandria, VA 22313-1450

*Please Enter
LT.
w/4/04*

Dear Sir:

This paper is filed in Notice of Allowance dated December 5, 2003.

Amendments to the Claims are reflected in the listing of Claims, which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.